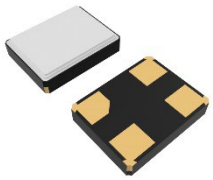
ABM8N series

LOW ESR, LOW CL CERAMIC SMD CRYSTAL

Description

The ABM8N series is an AT-Cut MHz quartz crystal offered in a 3.2mm x 2.5mm x 0.8mm four-pad SMD package. Tight frequency accuracy of ±10ppm and stability of ±15ppm over operating temperature range of -40°C to +85°C, low plating load (CL) value of 4pF, and low Equivalent Series Resistance (ESR) is achieved in this compact package. The ABM8N series offers industry standard frequencies common for wearables, IoT, Bluetooth / Bluetooth Low Energy (BLE), and Ultra-Low Power MCU's/SoC's/Transceivers end applications.



Features

- Optimized for energy saving wearables and IoT applications
- Plated at exceptionally low plating capacitance, as low as 4pF, with optimized ESR
- Seam sealed for long-term reliability
- REACH/RoHS II Compliant | MSL Level N/A

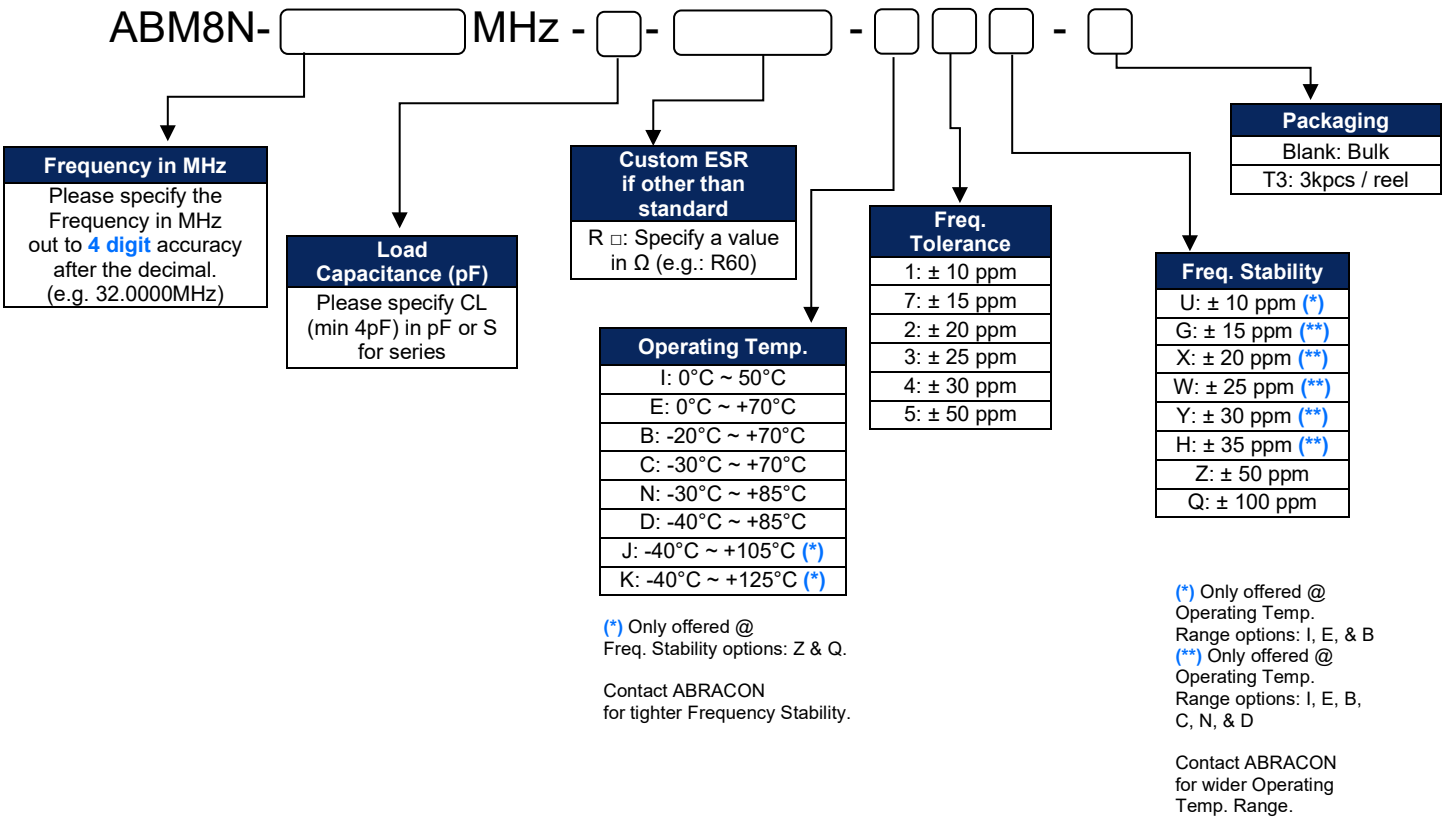
Typical Applications

- Wearables
- Wireless Modules
- Internet of Things (IoT)
- Bluetooth / Bluetooth Low Energy (BLE)
- Machine-to-Machine (M2M) Connectivity
- Ultra-Low Power MCU's, SoC's, Transceivers
- Near Field Communication
- ISM Band Applications

Electrical Specifications

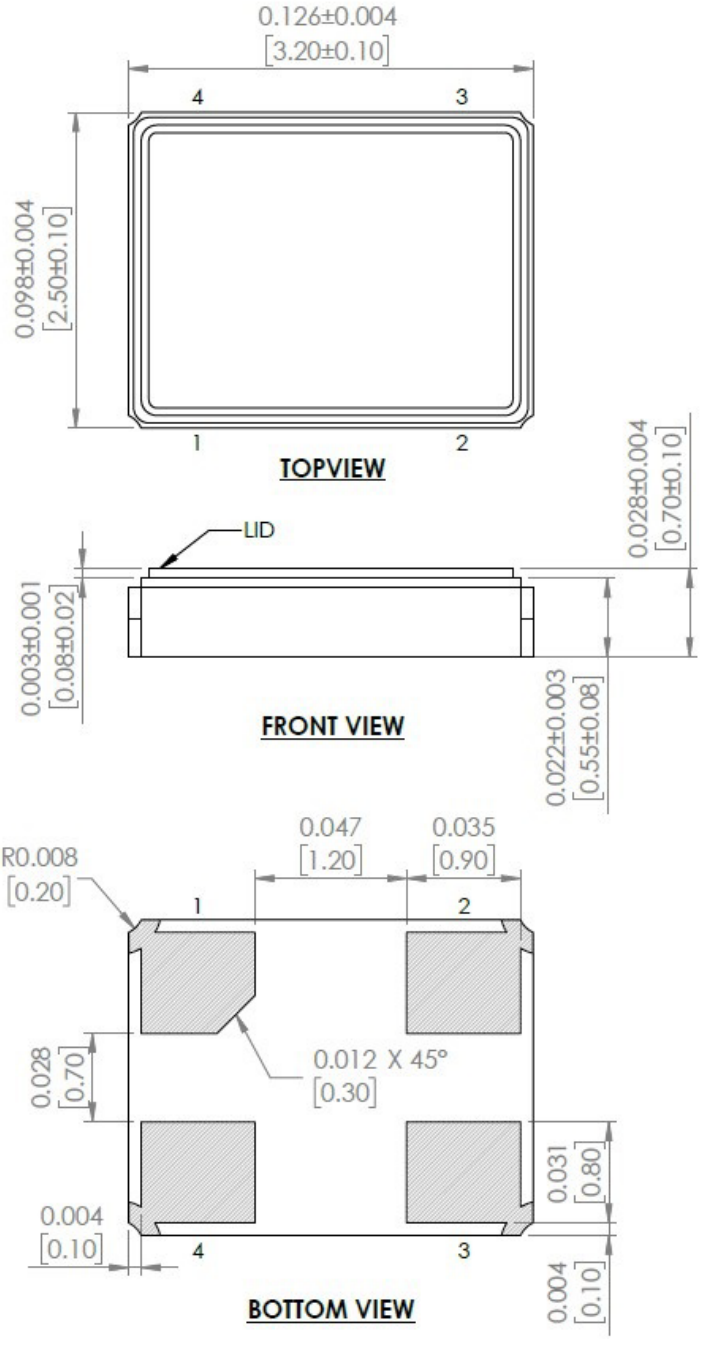
Parameters	Min.	Typ.	Max.	Units	Notes
Frequency Range	10.0000		54.0000	MHz	
Operation Mode		Fundamental			
Operating Temperature Range	-40		+125	ºC	See options
Storage Temperature	-55		+125	ºC	
Frequency Tolerance @ +25°C	-10		+10	ppm	See options
Frequency Stability over the Operating Temperature (ref. to +25°C)	-15		+15	ppm	See options
Equivalent series resistance "R1" (over -40ºC to +125°C)		< 100	200	Ω	10.0000 – 11.9999MHz
		< 60	100		12.0000 – 15.9999MHz
		< 40	70		16.0000 – 19.9999MHz
		< 25	50		20.0000 – 29.9999MHz
		< 20	40		30.0000 – 39.9999MHz
		< 18	40		40.0000 – 54.0000MHz
Shunt Capacitance (C0)		<1.2	2.0	pF	
Load Capacitance (CL)		4.0		pF	See options
Drive Level		10	100	µW	
Aging (1 year)	-2		+2	ppm	@ 25°C±3°C
Insulation Resistance	500			MΩ	@ 100Vdc±15V

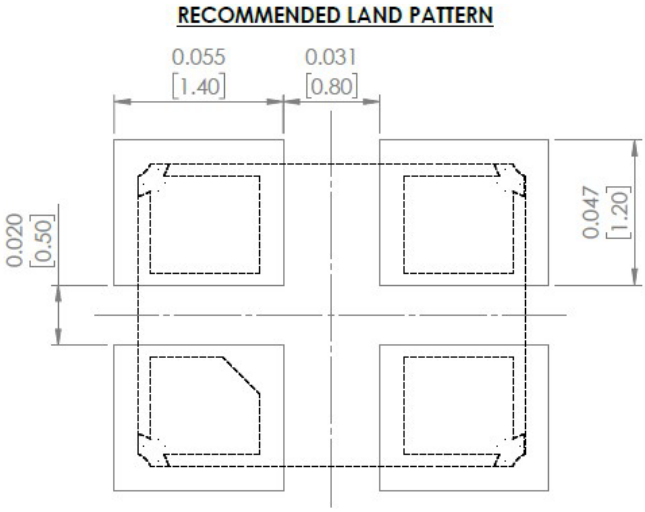
Part Identification [Note 1]



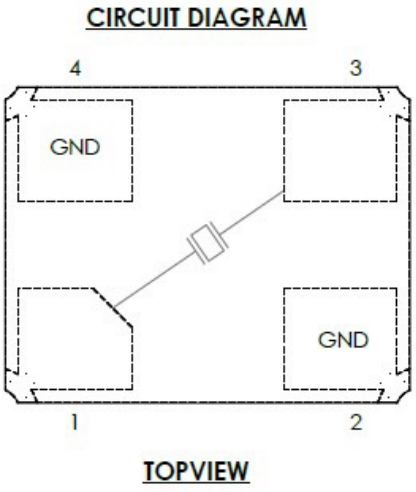
Note 1: Contact Abracon for part number requests with carrier frequency callouts up to 5 & 6 digit accuracy after the decimal.

Mechanical Dimensions





Pin #	Function
2	GND
4	GND



Dimensions: inches [mm]

Reflow Profile [JEDEC J-STD-020]

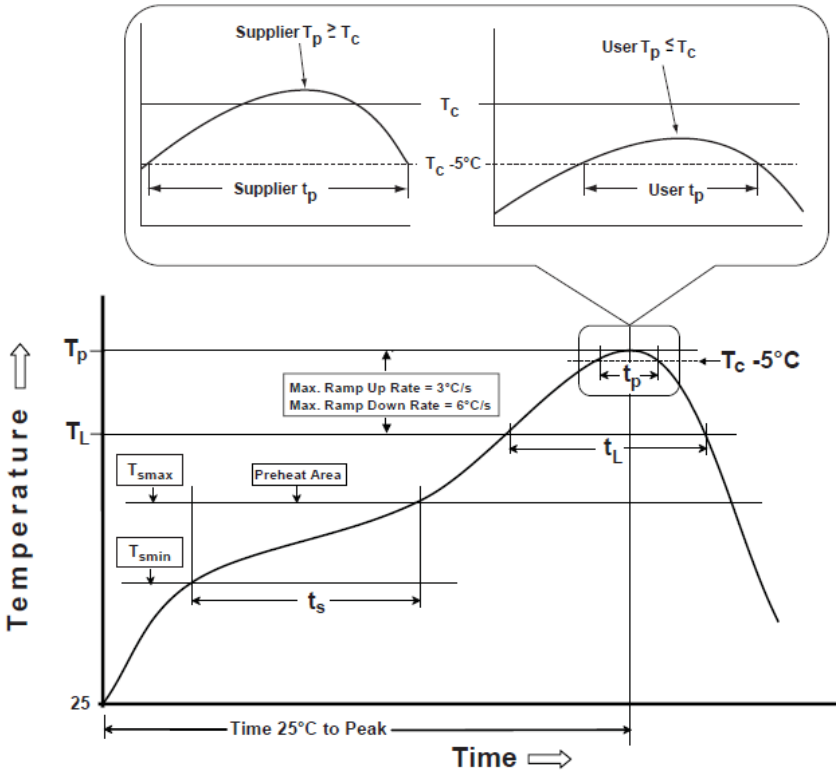


Table 1

SnPb Eutectic Process Classification Temperatures (T_c)		
Package Thickness	**Volume mm³ <350**	**Volume mm³ ≥350**
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2

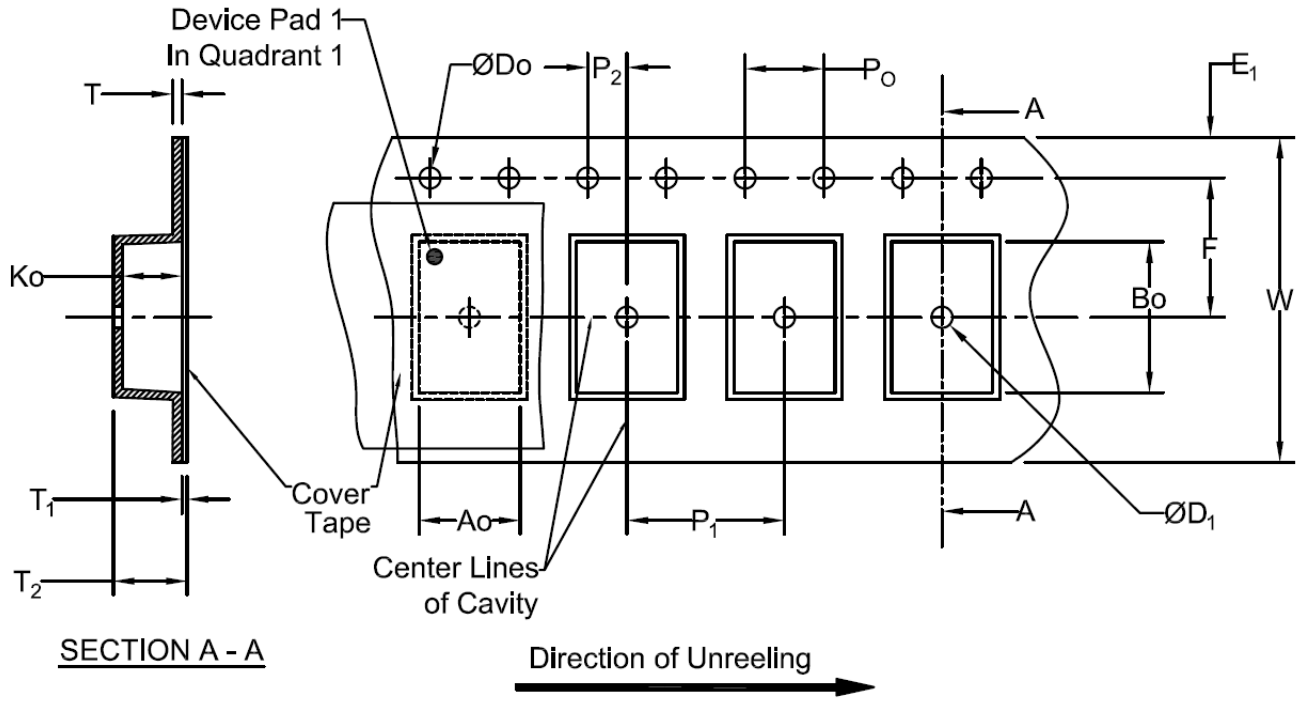
Pb-Free Process Classification Temperatures (T_c)			
Package Thickness	**Volume mm³ <350**	**Volume mm³ 350-2000**	**Volume mm³ >2000**
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T_{smin})	100°C	150°C
Temperature maximum (T_{smax})	150°C	200°C
Time (T_{smin} to T_{smax}) (t_s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T_{smax} to T_P)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T_P)*	**see Table 1**	**see Table 2**
Time (t_p)** within 5°C of the specified classification temperature (T_C)	20 sec.	30 sec.
Ramp-down rate (T_p to T_{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (t_p) is defined as supplier minimum and a user maximum.

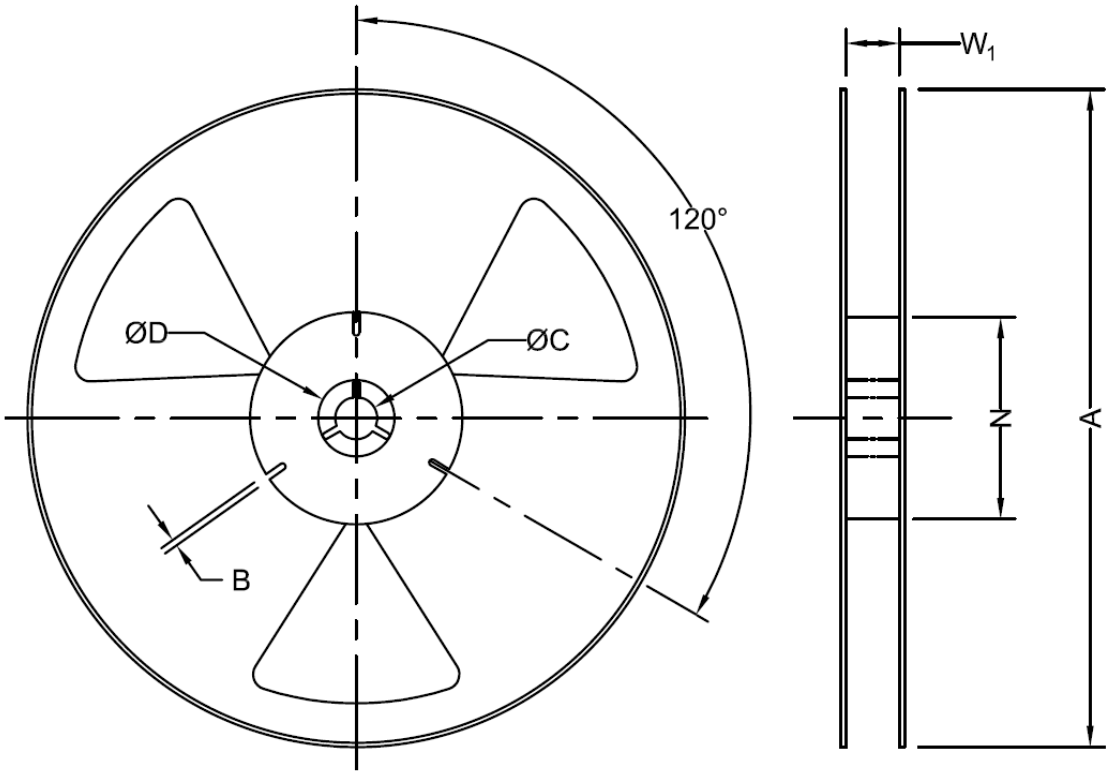
Packaging



Tape Specifications (mm)							
Width	**Ao**	**Bo**	**Do**	**D_1**	**E_1**	**F**	**Ko**
8mm	*	*	1.5+0.1/-0.0	1.0	1.75±0.1	3.5±0.05	*
Width	**P_1**	**P_2**	**P_0**	**T (Max)**	**T_1 (Max)**	**T_2 (Max)**	**W (Max)**
8mm	4.0±0.1	2.0±0.05	4.0±0.1	0.6	0.1	2.5	8.3

***Note: Compliant to EIA-481**

Packaging continued



Reel Specifications (mm)							
Width	**Qty/Reel**	**A (Nom)**	**B (Min)**	**C (Min)**	**D (Min)**	**N (Min)**	***W_1**
8mm	3000	178	1.5	13.0+0.5/-0.2	20.2	50	8.4+1.5/-0.0

***Note: Measured at Hub**